

27 - Line SCSI Terminator With Split Reverse Disconnect

FEATURES

- Complies with SCSI, SCSI-2, SCSI-3 and FAST-20 (Ultra) Standards
- 2.5pF Channel Capacitance During Disconnect
- 100 μ A Supply Current in Disconnect Mode
- 4V To 7V Operation
- 110 Ω Termination
- Completely Meets SCSI Hot Plugging
- -900mA Sourcing Current for Termination
- +500mA Sinking Current for Active Negation
- Logic Command Disconnects all Termination Lines
- Split Reverse Controls Lines 1 to 9 and 10 to 27 Separately
- Trimmed Impedance to 5%
- Current Limit and Thermal Shutdown Protection

DESCRIPTION

UCC5621 provides 27 lines of active termination for a SCSI (Small Computer Systems Interface) parallel bus. The SCSI standard recommends active termination at both ends of the cable.

The UCC5621 is ideal for high performance 5V SCSI systems. During disconnect the supply current is typically only 100 μ A, which makes the IC attractive for lower powered systems.

The UCC5621 features a split reverse disconnect allowing the user to control termination lines 10 to 27 with disconnect one, DISCNECT1, and control termination lines 1 to 9 with disconnect two, DISCNECT2.

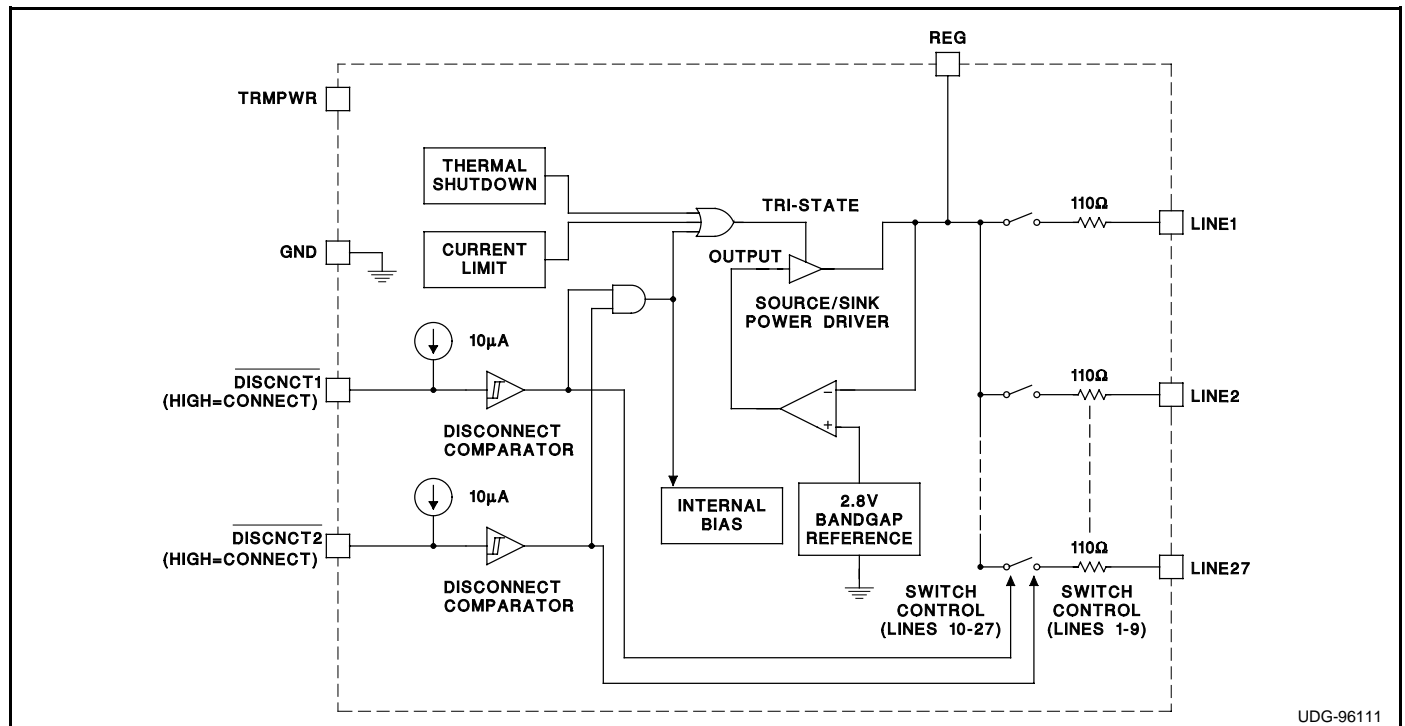
The UCC5621 is designed with a low channel capacitance of 2.5pF, which eliminates effects on signal integrity from disconnected terminators at interim points on the bus.

The power amplifier output stage allows the UCC5621 to source full termination current and sink active negation current when all termination lines are actively negated.

The UCC5621, as with all Unitrode terminators, is completely hot pluggable and appears as high impedance at the terminating channels with $V_{TRMPWR} = 0V$ or open.

continued

BLOCK DIAGRAM



UDG-96111

DESCRIPTION (cont.)

Internal circuit trimming is utilized, first to trim the 110Ω impedance, and then most importantly, to trim the output current as close to the maximum SCSI-3 specification as possible, which maximizes noise margin in FAST-20 SCSI operation.

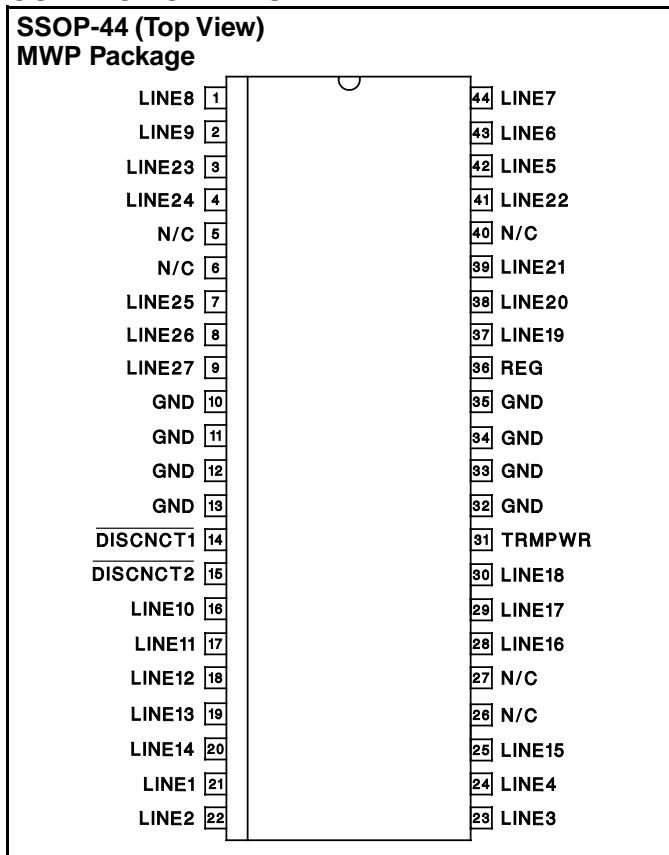
Other features include thermal shutdown and current limit. This device is offered in low thermal resistance versions of the industry standard 44 pin wide body SSOP (MWP). Consult SSOP-44 Packaging Diagram for exact dimensions.

ABSOLUTE MAXIMUM RATINGS

Tempwr Voltage	+7V
Signal Line Voltage	0V to +7V
Regulator Output Current	1.5A
Storage Temperature	-65°C to +150°C
Junction Temperature	-55°C to +150°C
Lead Temperature (Soldering, 10 Sec.)	+300°C

Currents are positive into, negative out of the specified terminal. Consult Packaging Section of Databook for thermal limitations and considerations of packages.

CONNECTION DIAGRAM



ELECTRICAL CHARACTERISTICS Unless otherwise stated, these specifications apply for TA = 0°C to 70°C, TRMPWR = 4.75V, DISCNCT1 = DISCNCT2 = 4.75V, TA = TJ.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Supply Current Section					
Tempwr Supply Current	All Termination Lines = Open		1	2	mA
	All Termination Lines = 0.2V		630	650	mA
Power Down Mode	DISCNCT1 = DISCNCT2 = 0V		100	200	μA
Output Section (Termination Lines)					
Termination Impedance	(Note 3)	104.5	110	115.5	Ω
Output High Voltage	(Note 1)	2.6	2.8	3.0	V
Max Output Current	VLINE = 0.2V, TJ = 25°C	-22.1	-23.3	-24	mA
	VLINE = 0.2V	-20.7	-23.3	-24	mA
	VLINE = 0.2V, TRMPWR = 4V, TJ = 25°C (Note 1)	-21	-23	-24	mA
	VLINE = 0.2V, TRMPWR = 4V (Note 1)	-20	-23	-24	mA
	VLINE = 0.5V			-22.4	mA
Output Leakage	DISCNCT1 = DISCNCT2 = 0V, TRMPWR = 0V to 5.25V		10	400	nA
Output Capacitance	DISCNCT1 = DISCNCT2 = 0V (Note 2)		2.5	4	pF
Regulator Section					
Regulator Output Voltage		2.6	2.8	3.0	V
Drop Out Voltage	All Termination Lines = 0.2V		0.4	0.8	V
Short Circuit Current	VREG = 0V	-650	-900	-1300	mA
Sinking Current Capability	VREG = 3.5V	300	500	900	mA
Thermal Shutdown			170		°C
Thermal Shutdown Hysteresis			10		°C

ELECTRICAL CHARACTERISTICS (cont.) Unless otherwise stated, these specifications apply for $T_A = 0^\circ\text{C}$ to 70°C , $\text{TRMPWR} = 4.75\text{V}$, $\text{DISCNCT1} = \text{DISCNCT2} = 4.7\text{V}$, $T_A = T_J$.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Disconnect Section					
Disconnect Threshold $\overline{\text{DISCNCT1}}$	Controls Lines 10 to 27	0.8	1.5	2.0	V
Input Current $\overline{\text{DISCNCT1}}$	$\overline{\text{DISCNCT1}} = 0\text{V}$		-10	-30	μA
Disconnect Threshold $\overline{\text{DISCNCT2}}$	Controls Lines 1 to 9	0.8	1.5	2	V
Input Current $\overline{\text{DISCNCT2}}$	$\overline{\text{DISCNCT2}} = 0\text{V}$		-10	-30	μA

Note 1: Measuring each termination line while other 26 are low (0.2V).

Note 2: Guaranteed by design. Not 100% tested in production.

Note 3: Tested by measuring I_{OUT} with $V_{\text{OUT}} = 0.2\text{V}$ and V_{OUT} with no load, then calculate:

$$Z = \frac{V_{\text{OUT N.L.}} - 0.2\text{V}}{I_{\text{OUT at 0.2V}}}$$

PIN DESCRIPTIONS

DISCNCT1: Disconnect one controls termination lines 10 – 27. Taking this pin low causes termination lines 10 – 27 to become high impedance, taking this pin high or leaving it open allows the channels to provide normal termination.

DISCNCT2 : Disconnect two controls termination lines 1 – 9. Taking this pin low causes termination lines 1 – 9 to become high impedance. Taking this pin high or leaving it

open allows the channels to provide normal termination. Taking both disconnect pins low will put the chip in to sleep mode where it will be in low-power mode.

GND: Ground reference for the IC.

LINE1 - 27: 110Ω termination channels.

REG: Output of the internal 2.7V regulator.

TRMPWR: Power for the IC.

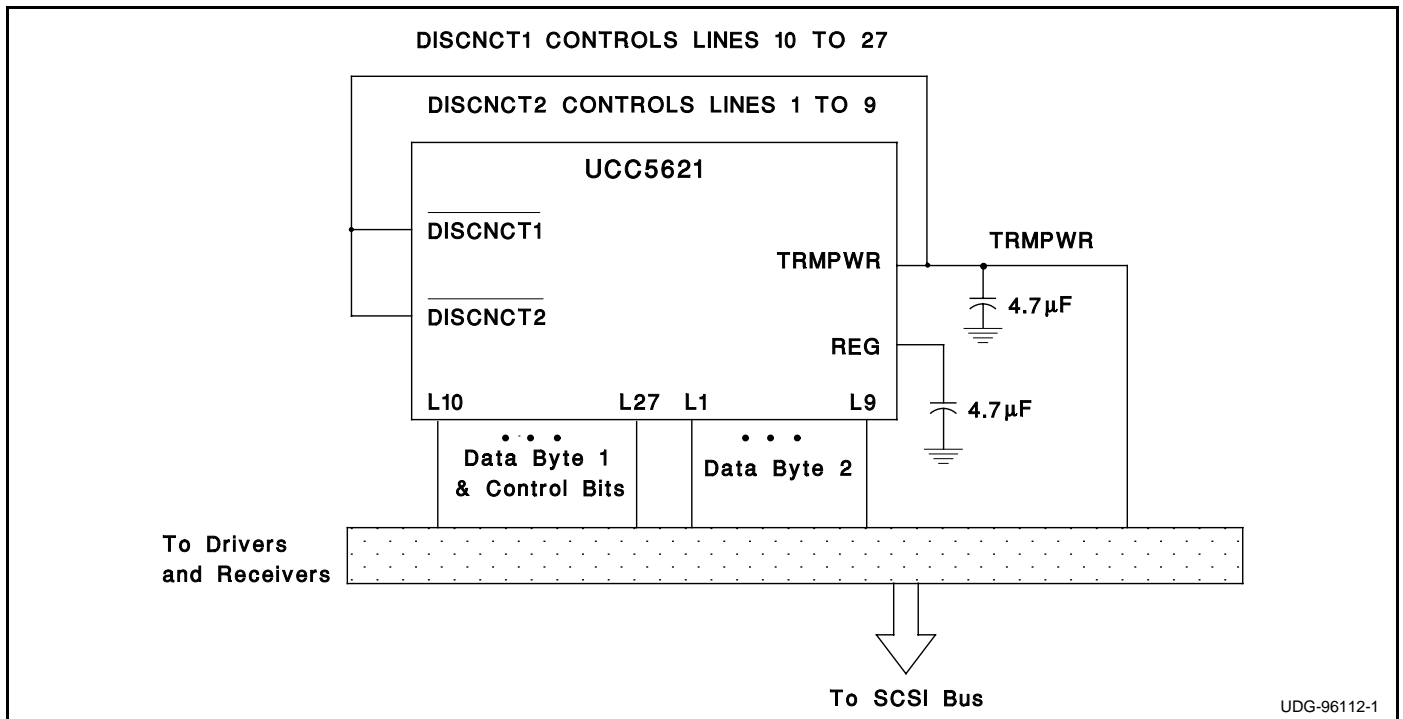
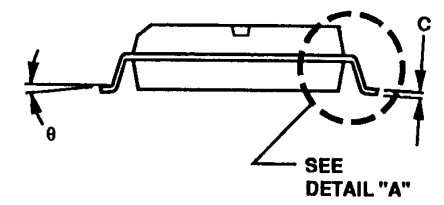
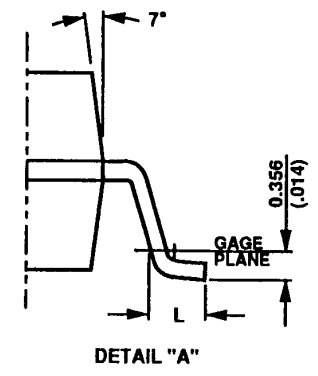
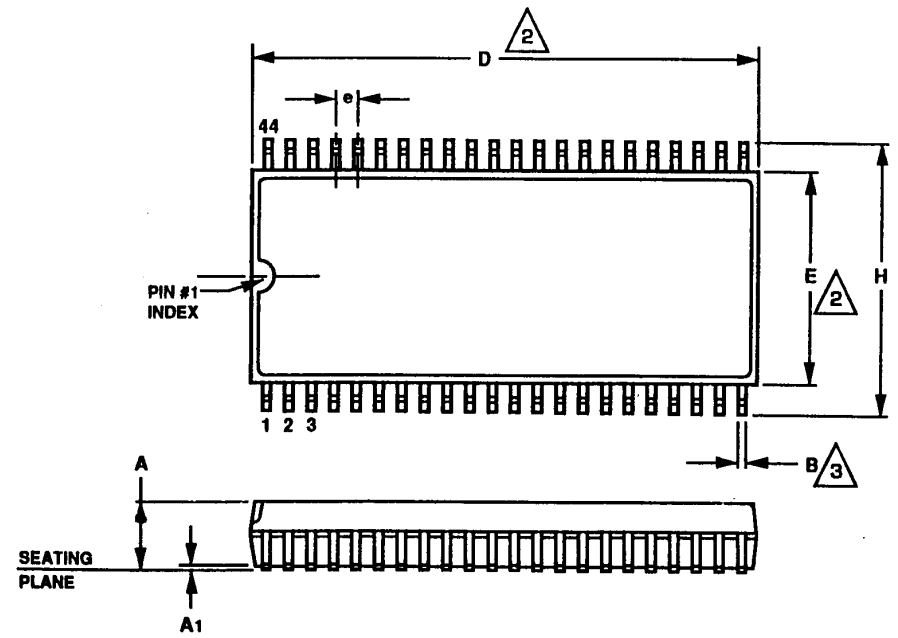


Figure 1. Typical Wide SCSI Bus Configuration Using the UCC5621

VENDOR	


REV. NO.	REVISIONS	DATE	APP'D.
-	INIT PER SCN #18179	01/15/98	

SYMBOL	DIMENSIONS			
	MIN		MAX	
	MM	INCHES	MM	INCHES
A	2.35	.093	2.65	.104
A1	0.10	.004	0.30	.012
B	0.28	.011	0.39	.015
C	0.15	.006	0.32	.0125
D	17.70	.697	18.10	.712
E	7.40	.291	7.60	.299
e	0.80 MM .031 INCHES BSC			
H	10.00	.394	10.65	.419
L	0.40	.016	1.27	.050
θ	0°		8°	



- NOTES:
- CONTROLLING DIMENSION: MILLIMETERS. INCHES SHOWN FOR REFERENCE.
 - 'D' AND 'E' DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15mm PER SIDE.
 - THE BASIC LEAD SPACING IS 0.80mm BETWEEN CENTERLINES. EACH LEAD CENTERLINE SHALL BE LOCATED WITHIN 0.20mm OF ITS EXACT TRUE POSITION AT MAXIMUM MATERIAL CONDITION RELATIVE TO THE CENTER OF THE PACKAGE BODY.
 - LEADS SHALL BE COPLANAR WITHIN 0.10mm AT THE SEATING PLANE.

DRAWN	RJV	DATE	1/98
APP'D	<i>RJM</i>	DATE	2/98
TOLERANCES (U.O.S.)			
.XX ± .01			
.XXX ± .005			
FRACTIONS ± 1/64"			
ANGLES ± 1/2°			
SURFACE QUALITY ✓			

 UNITRODE INTEGRATED CIRCUIT CORP. MERRIMACK, N.J.	
TITLE 44 LEAD SSOP PACKAGE OUTLINE DRAWING	
DWG NO. MA 2153	
SCALE	SHEET 1 OF 1